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(12) **United States Design Patent** (10) **Patent No.:** **US D501,450 S**
Watanabe et al. (45) **Date of Patent:** **** Feb. 1, 2005**

(54) **ELECTRONIC COMPONENT COOLING APPARATUS**

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(**) Term: **14 Years**

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(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/179**

(58) **Field of Search** D13/179; 165/80.3,
165/104.33, 121, 122, 146, 185; 257/697,
706, 707, 712, 718, 719, 720, 721, 722;
361/695, 697, 699, 702, 704, 709, 514

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(57) **CLAIM**

The ornamental design for a electronic component cooling apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front view of an electronic component cooling apparatus according to our new design;
FIG. 2 is a rear view thereof;
FIG. 3 is a right side view thereof;
FIG. 4 is a left side view thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof;
FIG. 7 is a perspective view thereof; and,
FIG. 8 is a cross-sectional view along line 8—8 of FIG. 5.

1 Claim, 8 Drawing Sheets

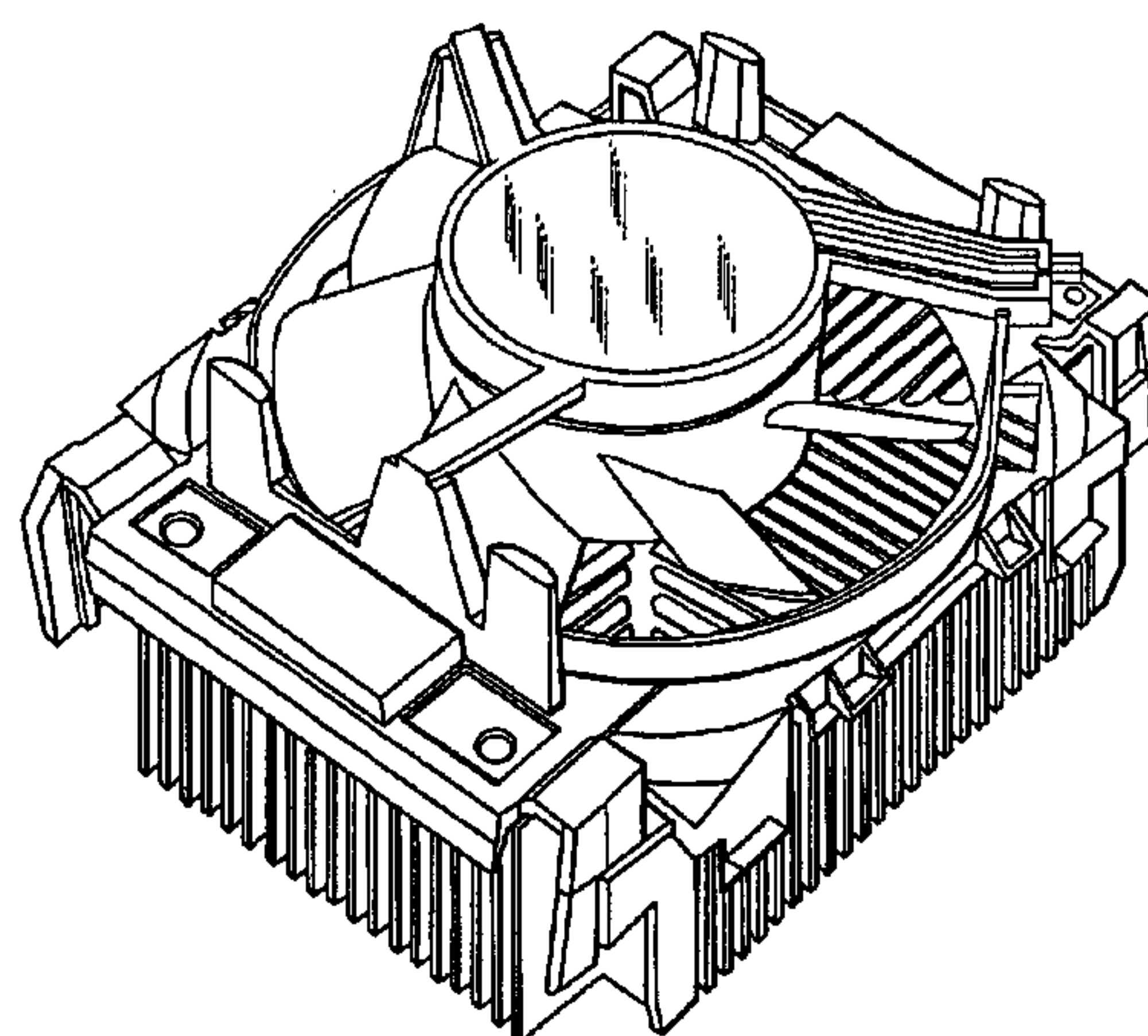
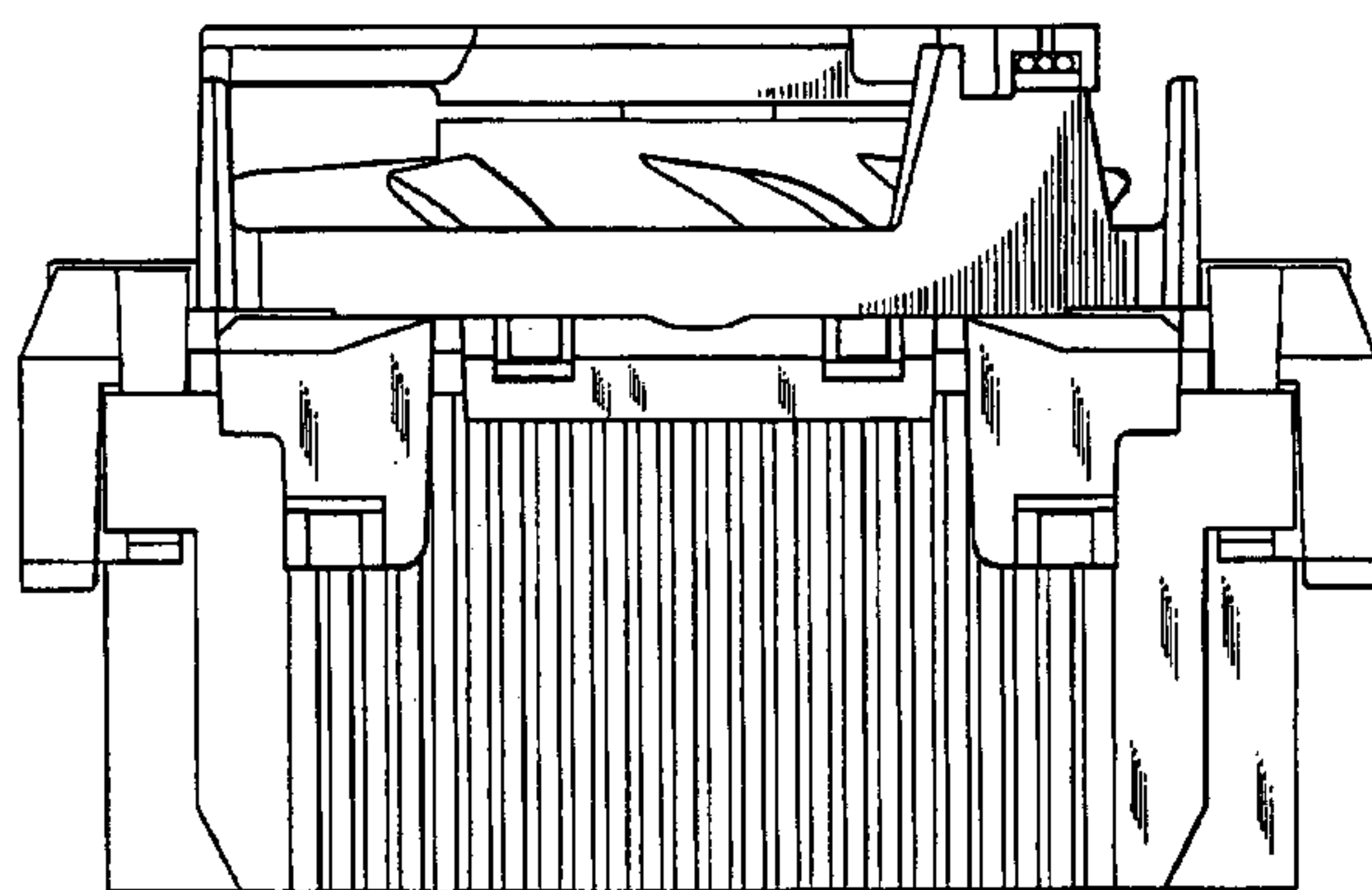


FIG.1

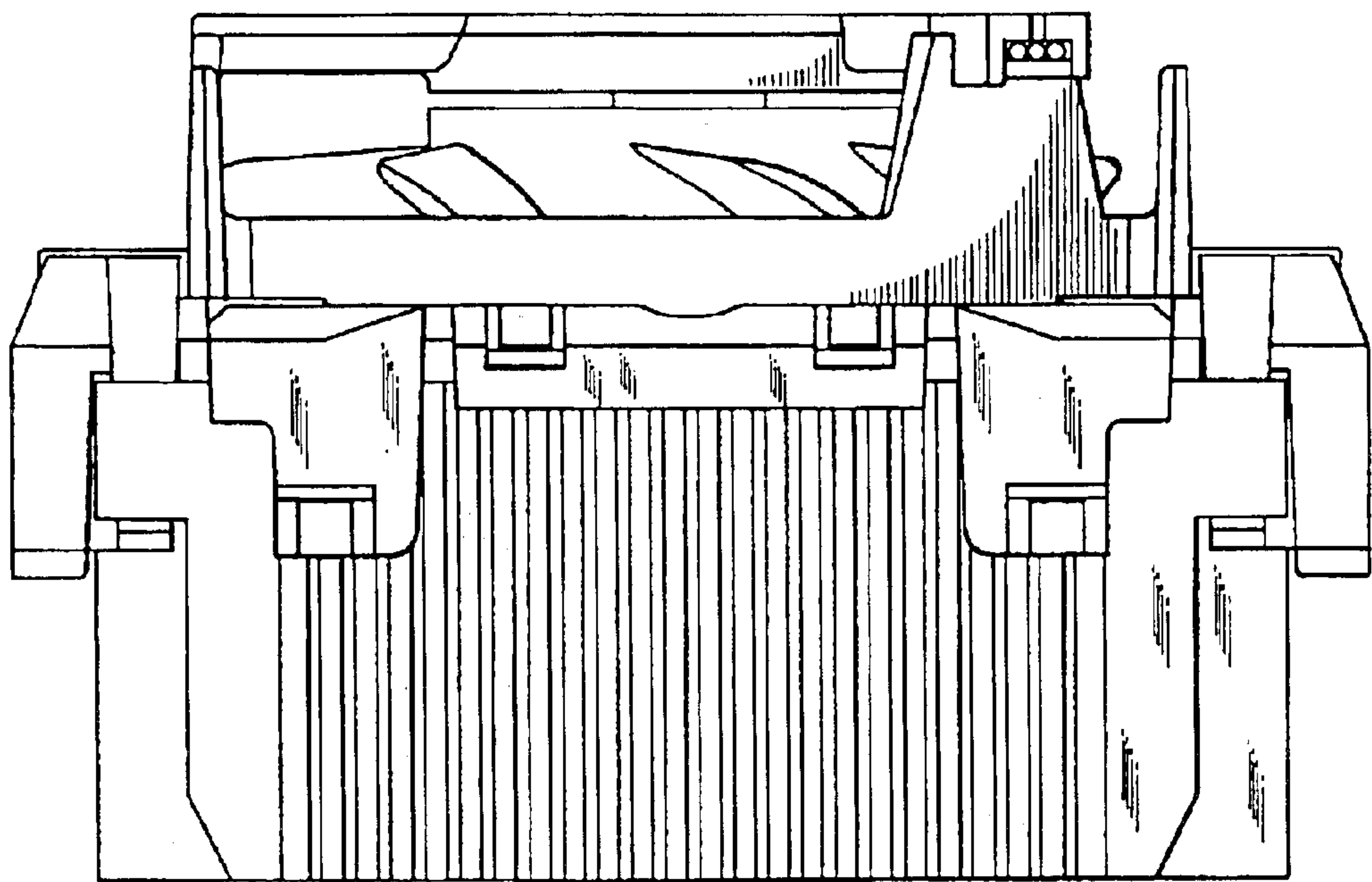


FIG.2

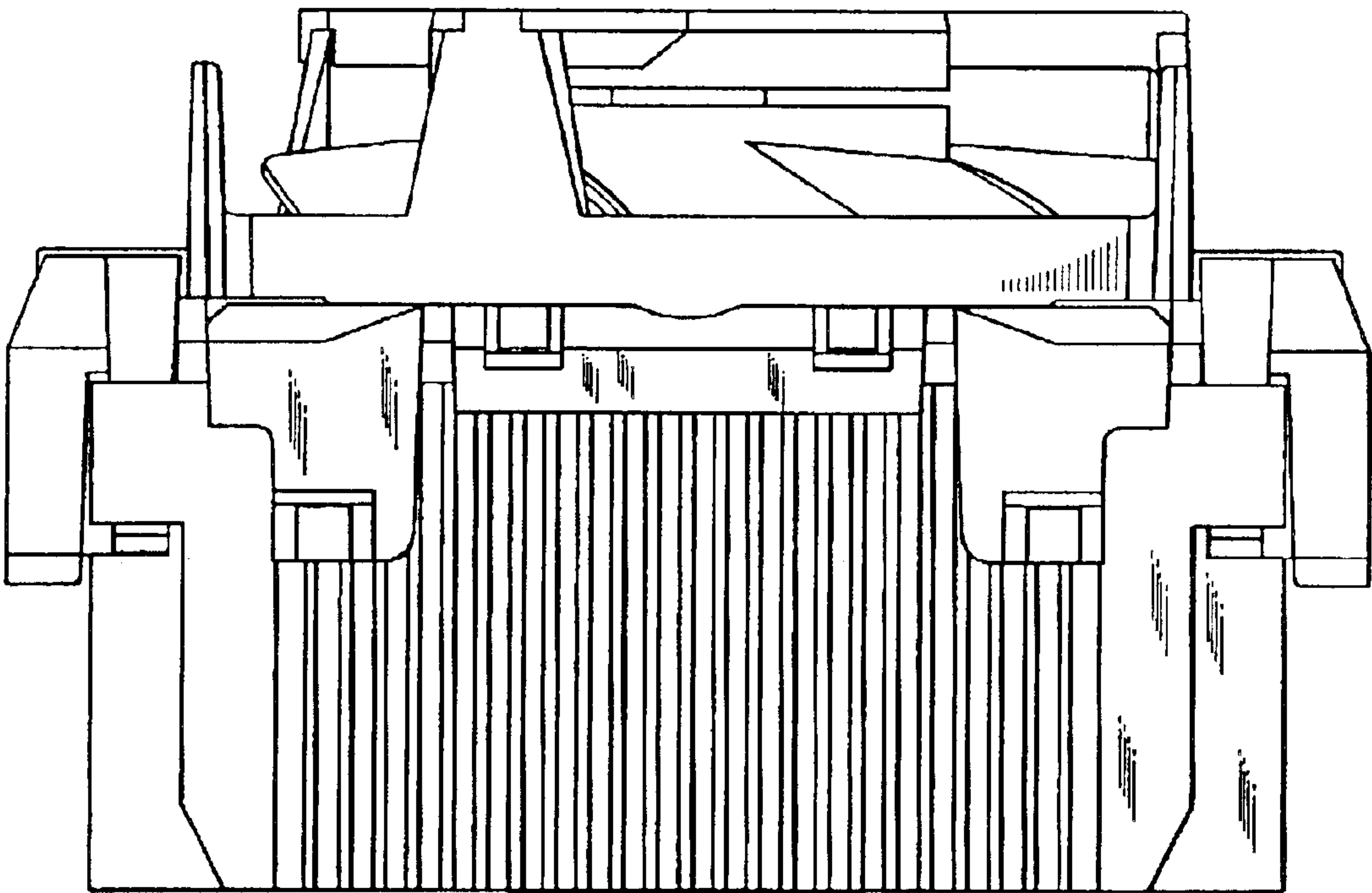


FIG.3

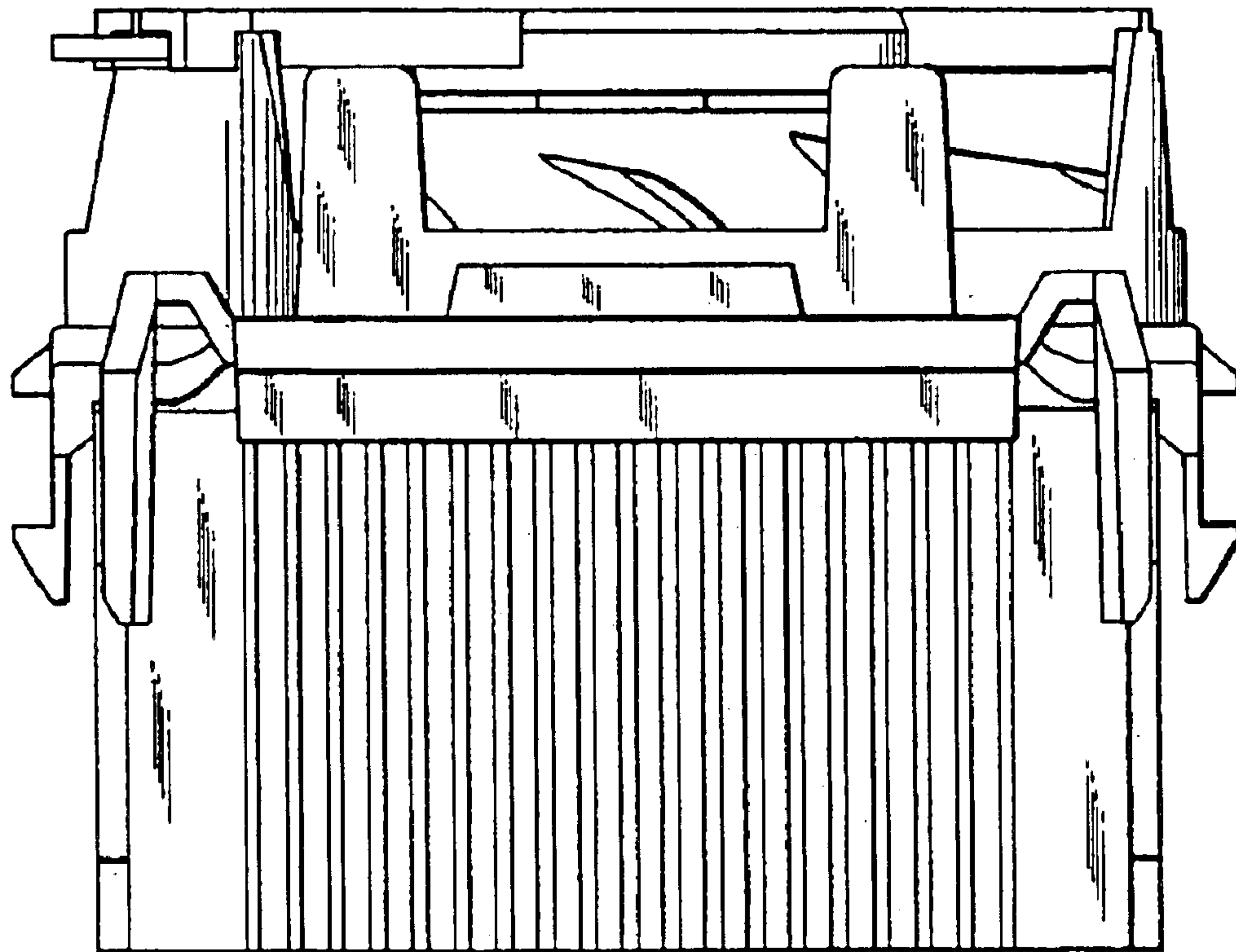


FIG.4

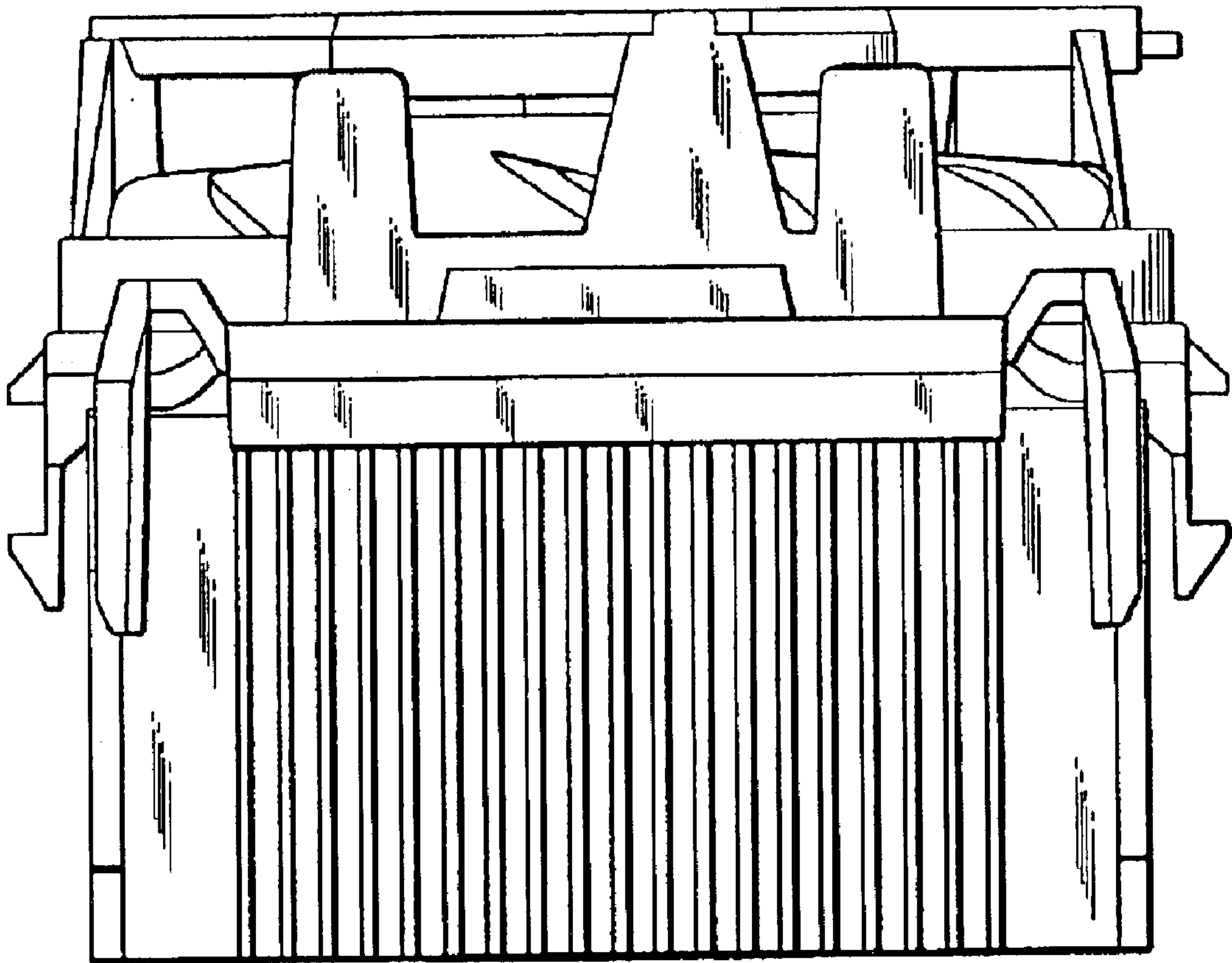


FIG.5

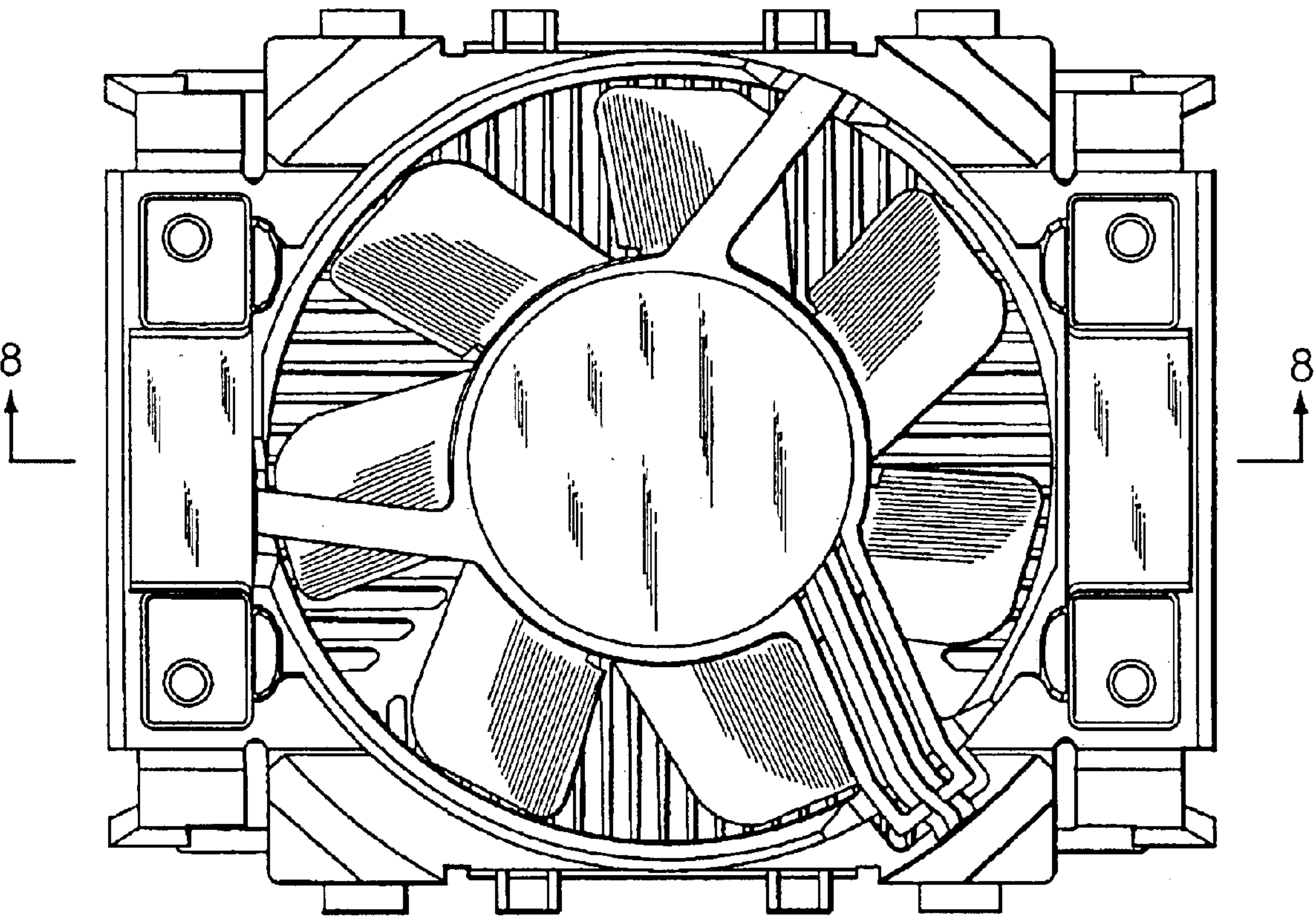


FIG.6

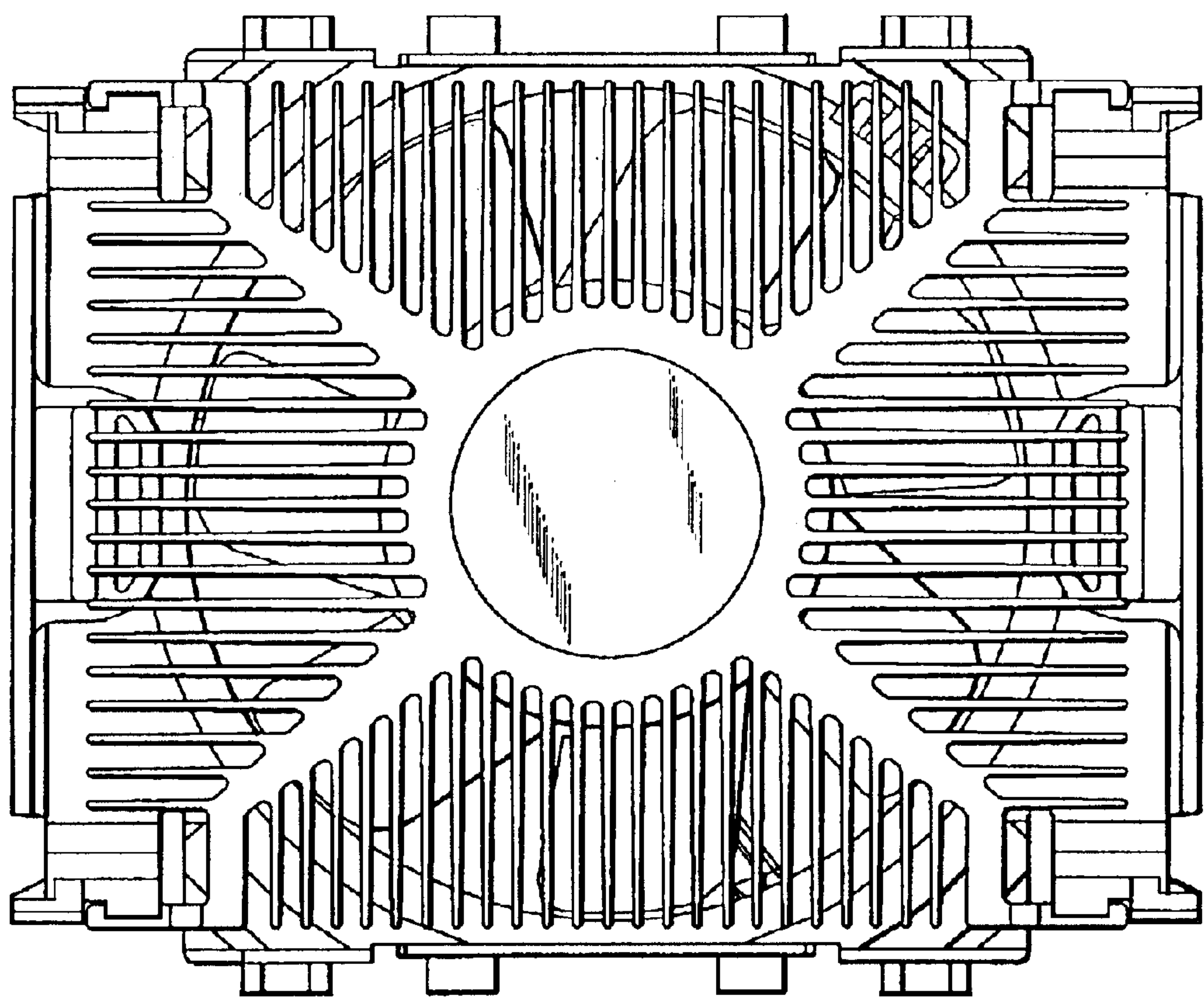


FIG.7

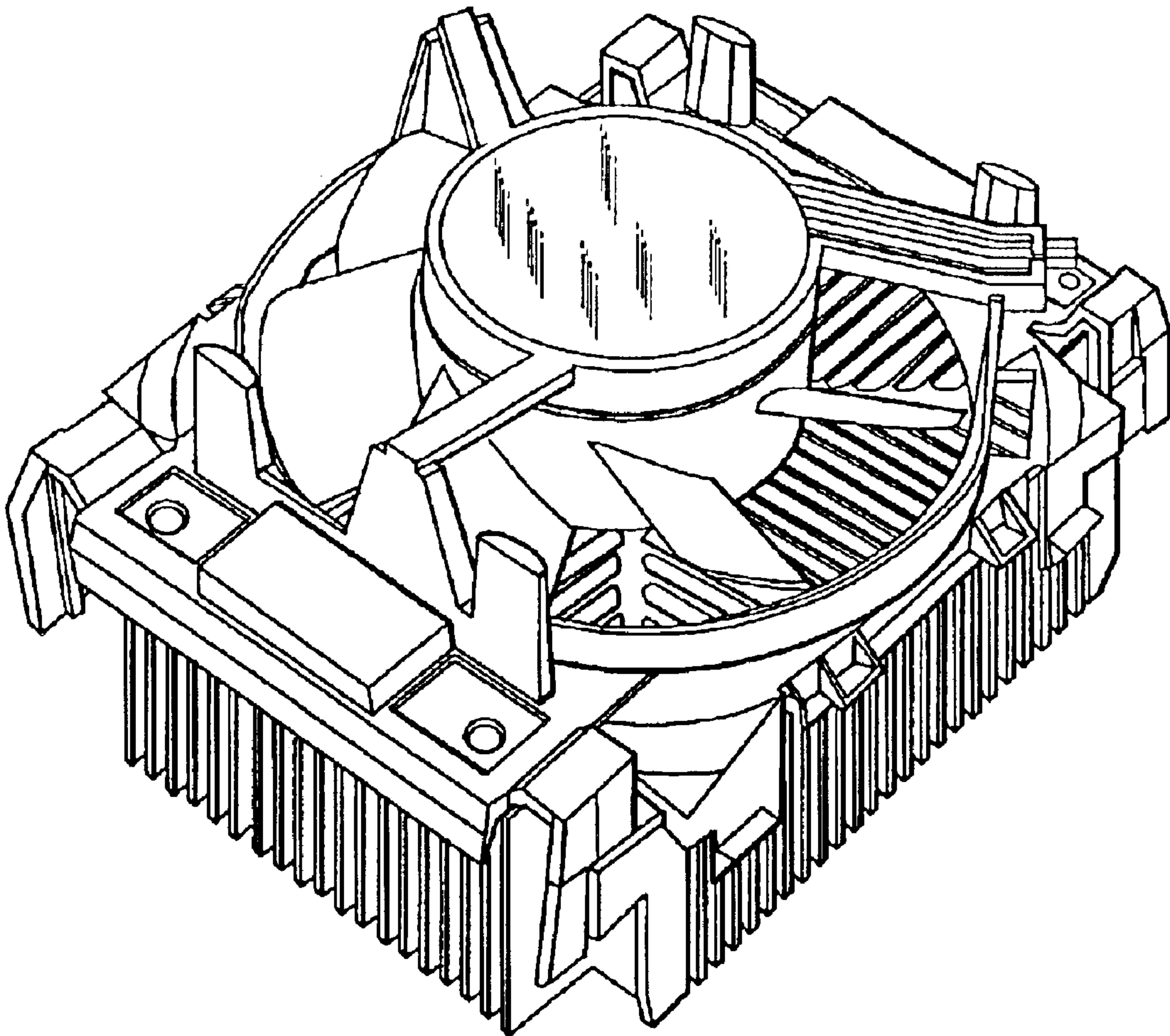


FIG.8

